

Microsemi Corporation

May 2017

Product/Process Change Notification No: PCN 2017-014

Change Classification: Minor

Subject: Bill of Material Epoxy Mold Change

Description of Change:

This is a change of mold compound used in Microsemi products listed products below. There is no change to the current approved assembly facility or any other materials used to produce these products. Package outline drawing of the affected products remain un-changed. Affected products will be fully compliant to all published data sheet specifications

Reason for Change: These changes were initiated by our assembly partner and are fully supported by Microsemi due to the advantages and benefits over the old materials.

Application Impact:

There is no change in form, fit and function, quality or reliability of the device. The device marking will remain unchanged

Method of Identifying Changed Product:

The parts that will be assembled will be identified by assembly lot and date code.

Products Affected by this Change:

All Commercial & HiRel Screening M/MA/MXL/MX level parts in the following Transient Voltage Suppressor series in both RoHS & non RoHS

SMBJ5.0A to SMBJ170A SMBJ5.0CA to SMBJ170CA SMCJ5.0A to SMCJ170A SMCG5.0A to SMCG170A SMCJ5.0CA to SMCJ170CA SMCG5.0CA to SMCG170CA SMLJ5.0A to SMLJ170A SMLG5.0A to SMLG170A SMLJ5.0CA to SMLJ170CA SMLG5.0CA to SMLG170CA

All M/MA/MXL/MX level parts RoHS & non RoHS in the following Transient Voltage Suppressor series:

MSMBJSAC5.0 thru MXLSMBJSAC75, MSMCJLCE6.5A thru MXLSMCJLCE170A. MSMCGLCE6.5A thru MXLSMCGLCE170A,

Note: This is a list of Ordering Part Numbers (OPNs) as are found in product datasheets. Customers may track additional part number variants in their systems, so please consider this a base part list.

Production Shipment Schedule:

Product with epoxy change is planned to ship no sooner than July 2017

During a transition period, customers may see shipments with older date while any existing inventory of parts is depleted.



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Qualification Data:

Summary of Qualification Results for Publication

	Qualification Data Summary							
Screening Level	Test Performed	Conditions	Duration or Qty	Standard / Ref	Sample size	No. Of Lots	Failures	
м	Temperature Cycle	-55 °C to +150 °C	1000 cycles	MIL-STD-750F Method 1051	77	3	0	
м	HTRB	125 °C	1000 hours	MIL-STD-750F Method 1038	77	3	0	
М	Autoclave	121 °C, 100 % RH, 15 psig	96 hours	JESD22-A102	77	3	0	
м	H*TRB	85°C, 85% RH, 15psig	1000 hours	JESD22-A101	77	3	0	
М	HAST	85°C, 85% RH	96 hours	85	77	1	0	
M	Resistance to Solder Heat	3		JESD22-B106	30	3	0	
м	Radiography	3 6	8	MIL-STD-750 Method 4081	30	2	0	
M	Solderability		18	J-STD-002	10	2	0	
MX	Physical Dimensions		3.53	MIL-STD-750F Method 2066	15	3	0	
MX	Terminal Strength		35	MIL-STD-750F Method 2036	22	1	0	
MX	Forward Surge Current	8.3ms half sine wave	1 repetition	MIL-STD-750 Method 4066 Condition A	22	3	0	
MX	Vcf Test, Forward voltage	Unidirectional only	1 repetition	MIL-STD-750 Method 4011	45	3	0	
MX	Surge Tests	100 % Im	100 repetitions	10/1000 µS waveform	22	2	0	
MX	High Temperature (non- operating)	150 °C	340 hours	MIL-STD-750F Method 1032	32	3	0	

Samples Availability:

Please contact your local Microsemi representative to place sample orders.

Contact Information:

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Regards,

Microsemi Corporation

Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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CHANGE APPROVAL SUPPLEMENT

Customer Acknowledgement / Approval for

Microsemi Corporation intends to implement this change 90 days after this notification. Acknowledgement of your company's acceptance of this change is requested per contractual agreement. Response within 30 days is required.

Accepted	Rejected	
Signature	 Date	
Name	Title	
Please enter rationale for	rejection, if applicable:	